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**(54)SEMICONDUCTOR DEVICE APPLICABLE
TO WAFER BURN-IN**

(57)Abstract

PROBLEM TO BE SOLVED: To perform a correct burn-in test with an IC chip as set, when a disorder takes place at burn-in test and an excessive current flows in a semiconductor device, allowing the excessive current to melt a fuse, so that a test current applied from a power source line is cut off.

SOLUTION: A wafer with a power source connected to each IC chip 1 is put in a specified high-temperature atmosphere, and a burn-in test is started. When a disorder takes place in the IC chip 1 during the test, an excessive current flows in a circuit element in the IC chip 1 from a power source line 4 through a proving pad 2. When the current exceeds a pre-set tolerable current of a fuse 5, it melts the fuse 5 and the current flowing

into the IC chip 1 from the power source line 4 is cut off. Thus, a correct burn-in test with the IC chip 1 is performed as set.

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